

10

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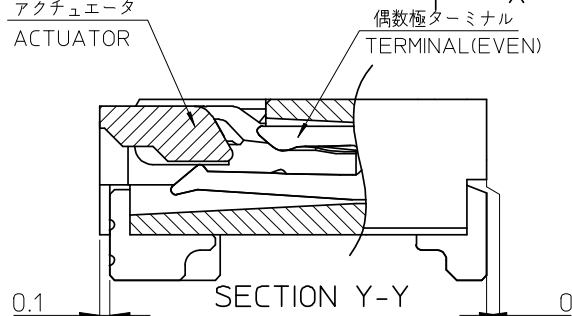
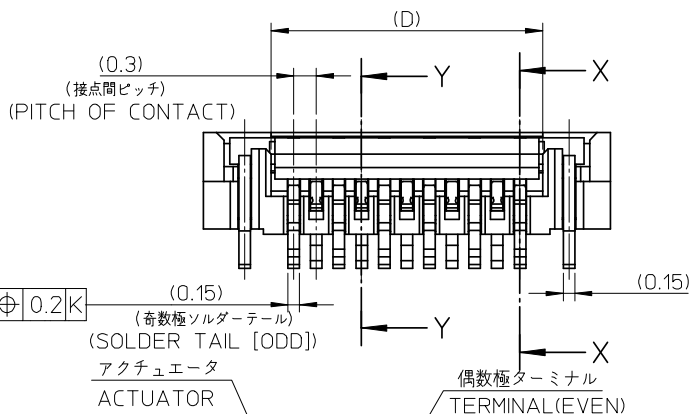
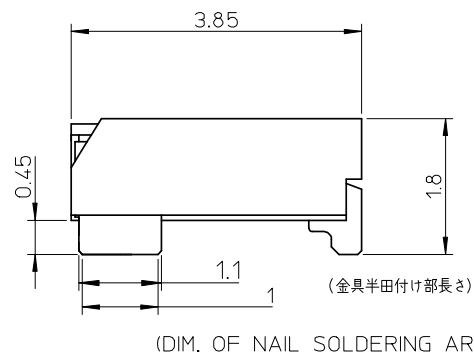
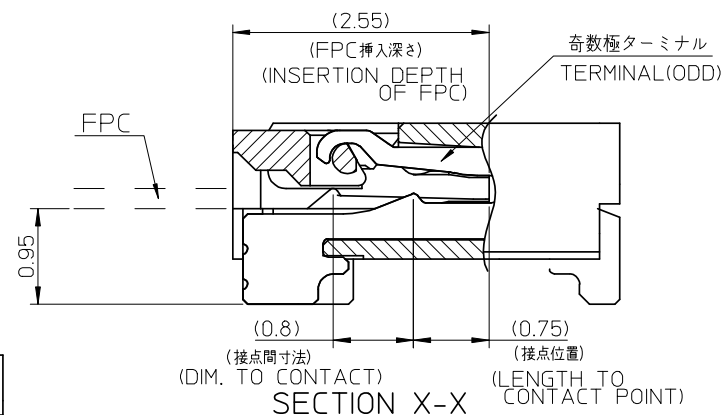
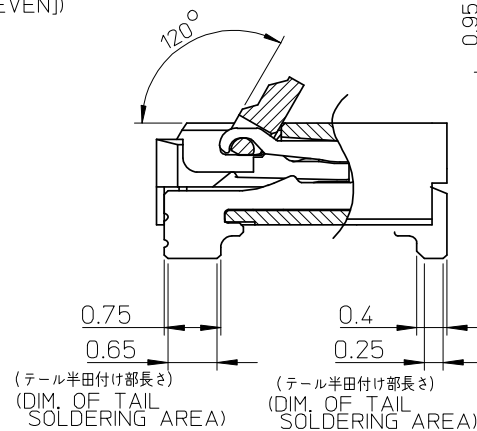
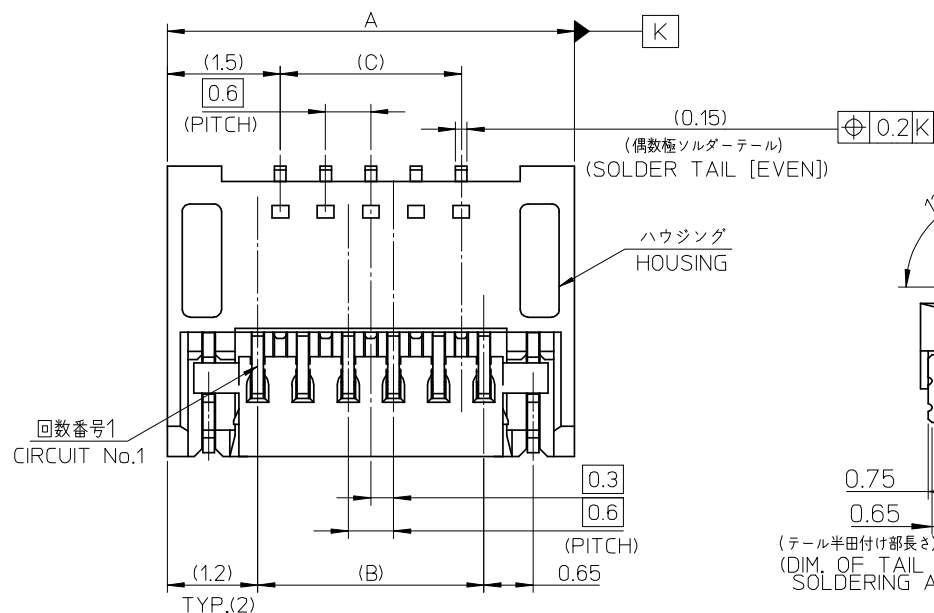
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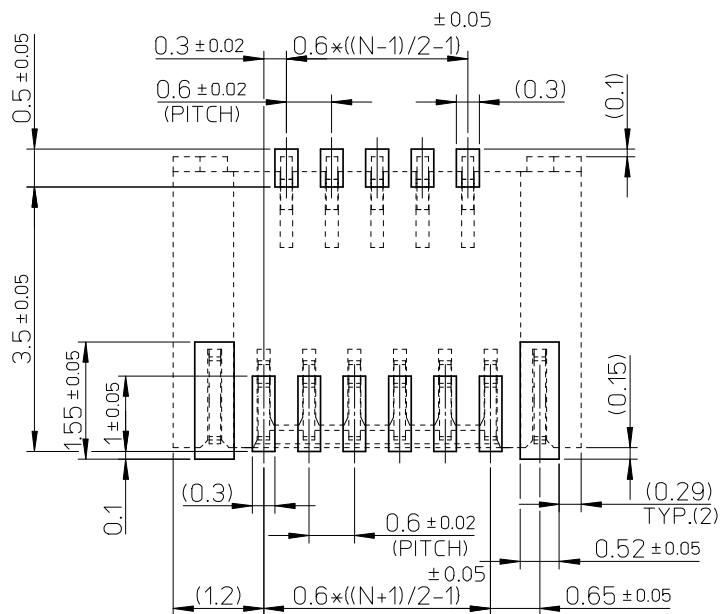
1



15.6	14.4	15.0	17.4	501912-5190	501912-5110	51
14.4	13.2	13.8	16.2	501912-4790	501912-4710	47
13.8	12.6	13.2	15.6	501912-4590	501912-4510	45
12.6	11.4	12.0	14.4	501912-4190	501912-4110	41
12.0	10.8	11.4	13.8	501912-3990	501912-3910	39
11.4	10.2	10.8	13.2	501912-3790	501912-3710	37
10.8	9.6	10.2	12.6	501912-3590	501912-3510	35
10.2	9.0	9.6	12.0	501912-3390	501912-3310	33
8.4	7.2	7.8	10.2	501912-2790	501912-2710	27
7.8	6.6	7.2	9.6	501912-2590	501912-2510	25
7.2	6.0	6.6	9.0	501912-2390	501912-2310	23
6.6	5.4	6.0	8.4	501912-2190	501912-2110	21
4.8	3.6	4.2	6.6	501912-1590	501912-1510	15
D	C	B	A	EMBOSS-TAPE PKG ORDER No.	MATERIAL No.	CIRCUIT

MODEL No. 501912-**10

REVISED EC NO: J2008-3324 DRAWN: HTAGAMI CHK'D: K TAKAHASHI APP'R: K TAKAHASHI	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 15:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY M. HAYASHI	DATE 2005/07/28	TITLE 0.3 FPC CONN E/O HSG ASSY (HGT=1.8MM) GOLDPLATING  MOLEX INCORPORATED			
		10 OVER 30 UNDER	± 0.25	CHECKED BY H. HIRATA	DATE 2005/07/28				
		30 OVER	± 0.3	APPROVED BY M. SASAO	DATE 2005/07/28				
		ANGULAR ±3 °		MATERIAL NO. SEE TABLE			DOCUMENT NO. SD-501912-001		SHEET NO. 1 OF 2
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



参考基板レイアウト図
(マウント面)
(MOUNTING SIDE)

注記 NOTES

1. 使用材料 MATERIAL

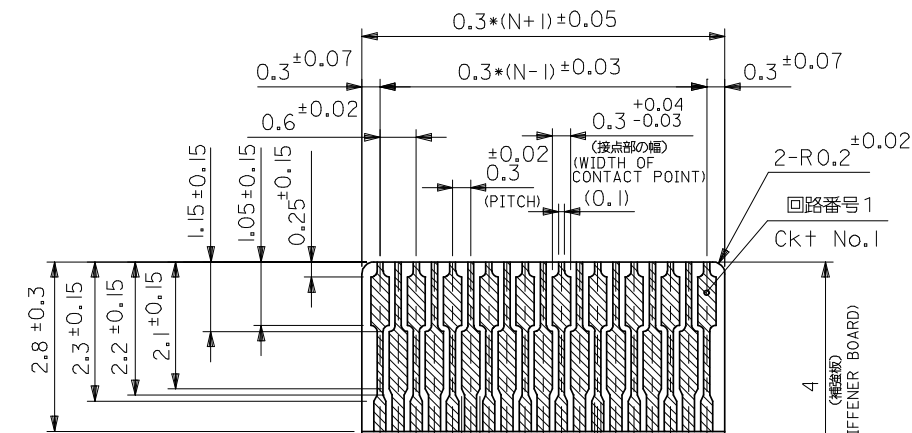
ハウジング : 耐熱性樹脂 ガラス充填 UL94V-0
HOUSING : HEAT RESISTANCE POLYMER (GLASS FILLED) UL94V-0
アクチュエータ : 耐熱性樹脂 ガラス充填 UL94V-0
ACTUATOR : HEAT RESISTANCE POLYMER (GLASS FILLED) UL94V-0
ターミナル : 銅合金 (t=0.15), ニッケル下地金メッキ
TERMINAL : COPPER ALLOY, GOLD OVER NICKEL PLATING.
金具 : 銅合金 (t=0.15), ニッケル下地スズメッキ
FITTING NAIL : COPPER ALLOY, TIN OVER NICKEL PLATING.

ハウジングに黒点がある場合が有りますが、問題はありません。

2. ソルダータール半田付け面、及び金具半田付け面の平坦度 : 0.1mm MAXIMUM.

COPLANARITY OF SOLDER TAILS AND FITTING NAILS
TO BE 0.1mm MAXIMUM.

3. ELV AND RoHS COMPLIANT.



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ : 0.2 ± 0.03)
(THICKNESS: 0.2 ± 0.03)

FPCについて :

打抜き方向は導体側から補強板側を推奨いたします。
導体部については軟銅箔35マイクロメートルまたは50マイクロメートルを
推奨致します。
補強フィルム材質はポリイミドを推奨します。
接着剤は熱硬化接着剤を推奨します。

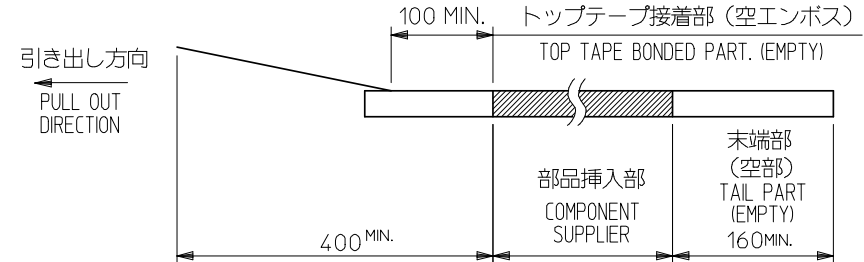
ABOUT FPC

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPEC :
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

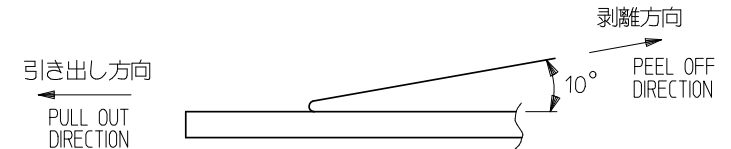
REVISED	EC NO. J2008-3324	DRAWN:HTAGAMI CHKD:KATAHASHI APPR:KATAHASHI	2008/03/25 2008/04/07 2008/04/07	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE -----	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
					10 UNDER	± 0.2	DRAWN BY M.HAYASHI	DATE 2005/07/28	TITLE 0.3 FPC CONN E/O HSG ASSY (HGT=1.8MM) GOLDPLATING			
					10 OVER 30 UNDER	± 0.25	CHECKED BY H.HIRATA	DATE 2005/07/28				
					30 OVER	± 0.3	APPROVED BY M.SASAO	DATE 2005/07/28	MOLEX MOLEX INCORPORATED			
					ANGULAR ±3 °		MATERIAL NO.					
					DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-501912-001		2 OF 2	
							SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

NOTES

- 製品詳細寸法は製品単体図面を参照して下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS,PLEASE SEE THE DRAWING OF CONNECTOR ITSELF(NOT PACKAGED).
- 梱包数量：3000個／リール
NUMBER OF CONNECTORS：3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



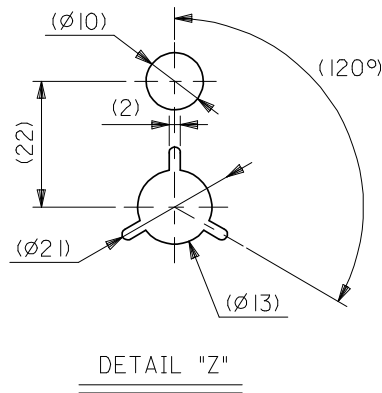
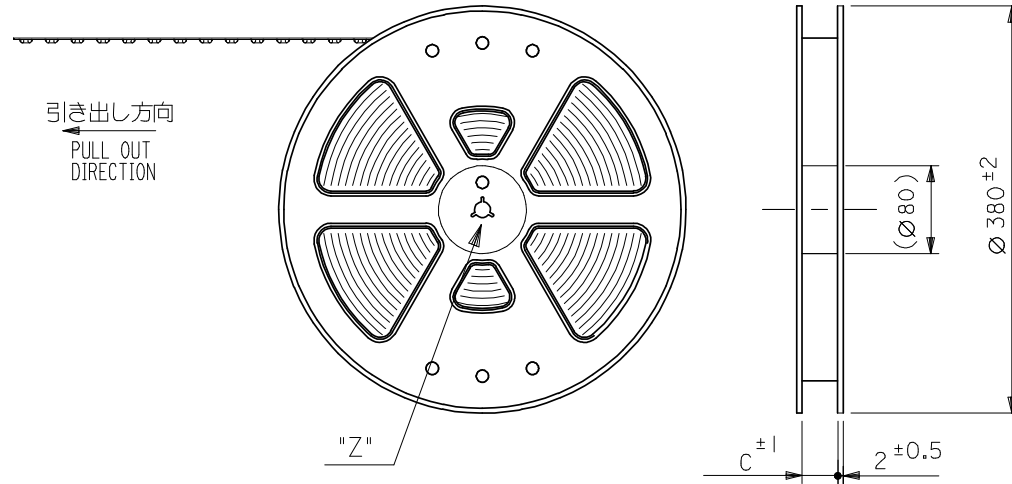
- トップテープの剥離強度：60±35gf (0.25N～0.93N) (剥離方向は下図参照) 尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE：65gf±30gf (0.25N～0.93N) (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.) THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT. PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.



5. 材料(MATERIAL)

キャリアテープ (CARRIER TAPE)：ポリスチレン (POLYSTYREN)
トップテープ (TOP TAPE)：PET, PE, PEF
リール(REEL)：ポリスチレン(PS) <リサイクル材を含む>
POLYSTYREN(PS) <RECYCLE MATERIAL CONTAINED>

- C寸法は SHEET 2～4を参照下さい。
SEE SHEET 2～4(DIMENSION C).
- ELV AND RoHS COMPLIANT.



REVISED EC NO: J2008-3324 DRAWN: HTAGAMI CHKD: K TAKAHASHI APPR: K TAKAHASHI	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	501912-**90 DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	MODEL NO.	
		10 UNDER	± 0.2	DRAWN BY M. HAYASHI	DATE 2005/10/11	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING				
		10 OVER 30 UNDER	± 0.25	CHECKED BY H. HIRATA	DATE 2005/10/11					
		30 OVER	± 0.3	APPROVED BY M. SASAO	DATE 2005/10/11					
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-501912-002		1 OF 4		
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

F

E

D

C

B

A

F

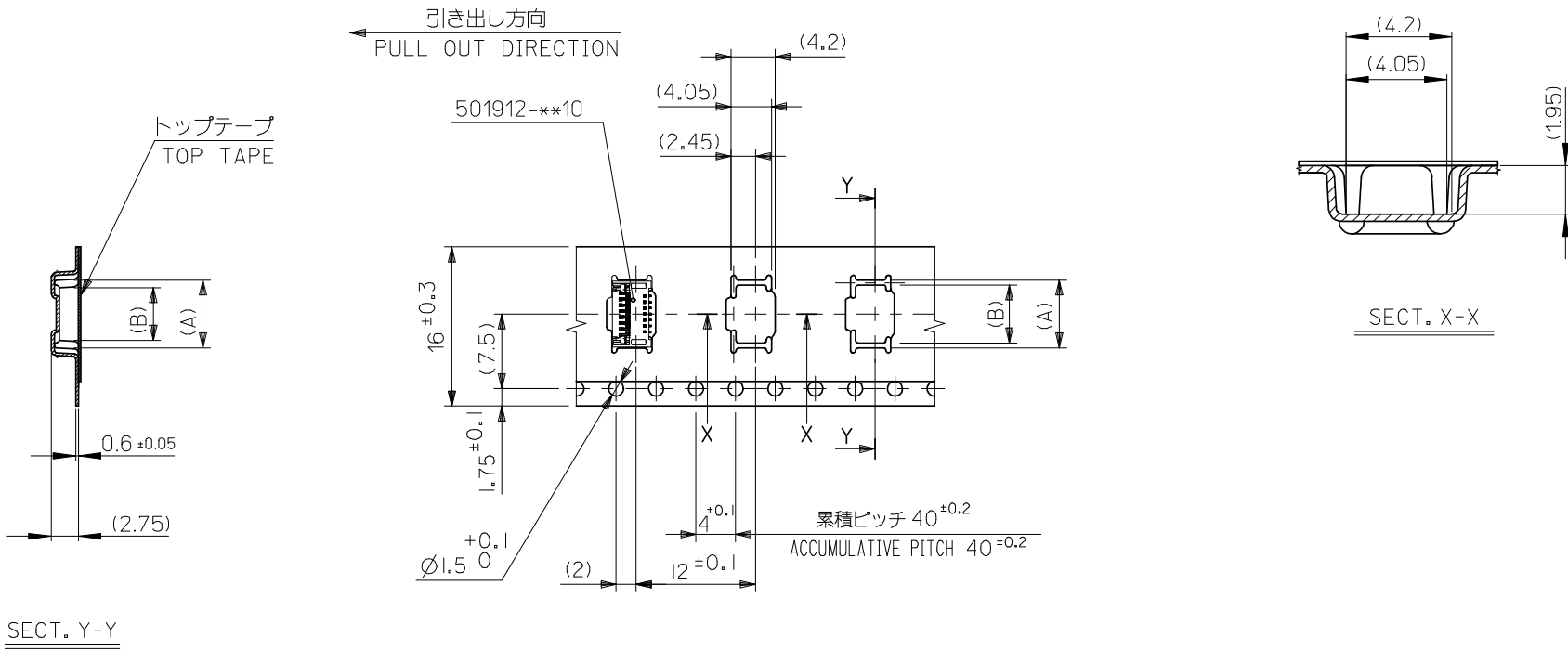
E

D

C

B

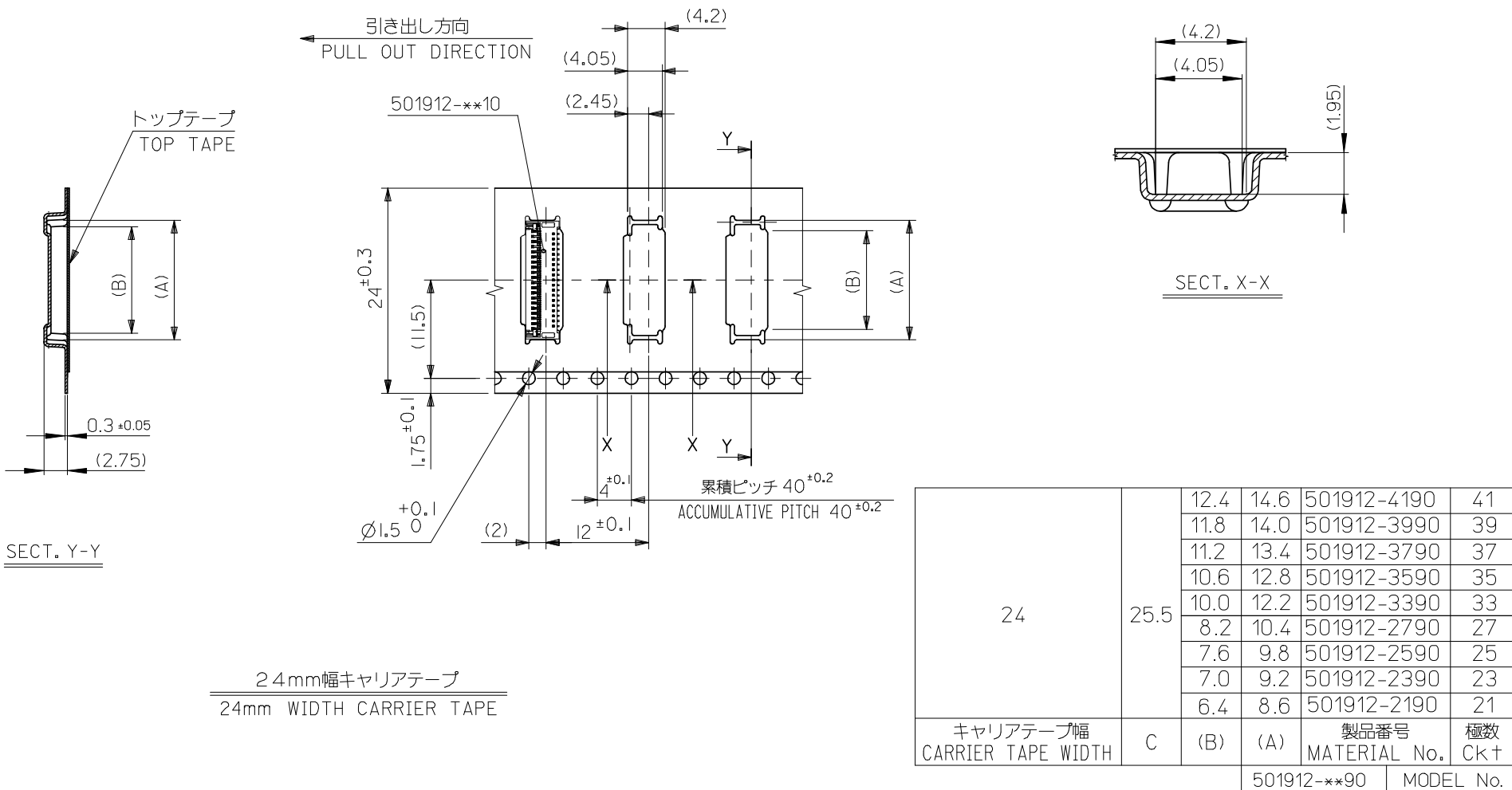
A



16 mm幅キャリアテープ
16mm WIDTH CARRIER TAPE

16	17.5	4.6	6.8	501912-1590	15
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	製品番号 MATERIAL No.	極数 CK+
501912-**-90				MODEL No.	

REVISED EC NO: J2008-3324 DRAWN: HTAGAMI 2008/03/25 CHKD: KITAKAHASHI 2008/04/07 APPR: KITAKAHASHI 2008/04/07	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY M. HAYASHI	DATE 2005/10/11	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING				
		10 OVER 30 UNDER	± 0.25	CHECKED BY H. HIRATA	DATE 2005/10/11					
		30 OVER	± 0.3	APPROVED BY M. SASAO	DATE 2005/10/11	MOLEX INCORPORATED				
		ANGULAR ± 3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-501912-002		2 OF 4		
		REV		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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